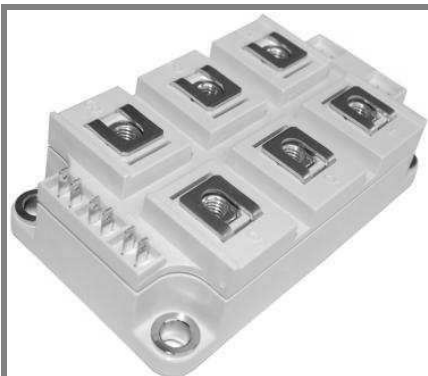


# SKM300MLI066TAT



**SEMITRANS® 5**

## Trench IGBT Modules

**SKM300MLI066TAT**

### Features

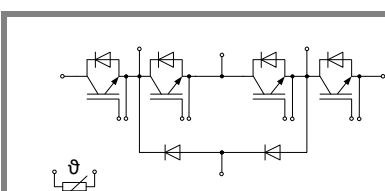
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$  with positive temperature coefficient
- Integrated NTC temperature sensor

### Typical Applications\*

- UPS
- 3 Level Inverter

### Remarks

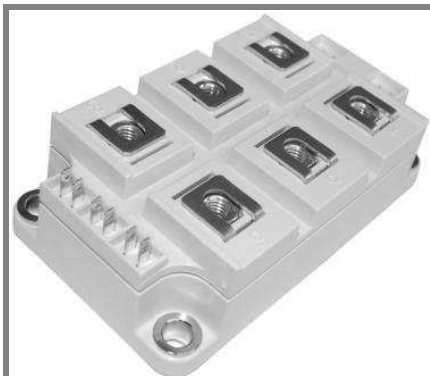
- Case temperature limited to  $T_c = 125^\circ\text{C}$  max
- Recommended  $T_{op} = -40..+150^\circ\text{C}$  for IGBT;  
 $T_{op} = -40..+125^\circ\text{C}$  for diode
- $T_{vj}$  is intended as absolute maximum rating, limited by diode
- Fig.2 is referred to IGBT current capability



**MLI-TAT**

Absolute Maximum Ratings				$T_{case} = 25^\circ\text{C}$ , unless otherwise specified	
Symbol	Conditions			Values	Units
<b>IGBT</b>					
$V_{CES}$	$T_j = 25^\circ\text{C}$			600	V
$I_C$	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$		400	A
		$T_c = 80^\circ\text{C}$		300	A
$I_{CRM}$	$I_{CRM} = 2 \times I_{Cnom}$			600	A
$V_{GES}$				$\pm 20$	V
$t_{psc}$	$V_{CC} = 360\text{ V}; V_{GE} \leq 15\text{ V}; T_j = 150^\circ\text{C}$ $V_{CES} < 600\text{ V}$			6	$\mu\text{s}$
<b>Inverse Diode</b>					
$I_F$	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$		324	A
		$T_c = 80^\circ\text{C}$		211	A
$I_{FRM}$	$I_{FRM} = 2 \times I_{Fnom}$			420	A
$I_{FSM}$	$t_p = 10\text{ ms}; \text{half sine wave } T_j = 150^\circ\text{C}$			2100	A
<b>Freewheeling Diode</b>					
$I_F$	$T_j = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$		324	A
		$T_c = 80^\circ\text{C}$		211	A
$I_{FRM}$	$I_{FRM} = 2 \times I_{Fnom}$			420	A
$I_{FSM}$	$t_p = 10\text{ ms}; \text{half sine wave } T_j = 150^\circ\text{C}$			2100	A
<b>Module</b>					
$I_{t(RMS)}$				500	A
$T_{vj}$				- 40 ... + 150	$^\circ\text{C}$
$T_{stg}$				- 40 ... + 125	$^\circ\text{C}$
$V_{isol}$	AC, 1 min.			2500	V

Characteristics			T <sub>case</sub> = 25°C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
V <sub>GE(th)</sub>	V <sub>GE</sub> = V <sub>CE</sub> , I <sub>C</sub> = 4,8 mA		5	5,8	6,5	V
I <sub>CES</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = V <sub>CES</sub>	T <sub>j</sub> = 25 °C			0,5	mA
I <sub>GES</sub>	V <sub>CE</sub> = 0 V, V <sub>GE</sub> = 20 V	T <sub>j</sub> = 25 °C			1200	nA
V <sub>CE0</sub>		T <sub>j</sub> = 25 °C		0,9	1	V
		T <sub>j</sub> = 150 °C		0,85	0,9	V
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C		1,8	3	mΩ
		T <sub>j</sub> = 150°C		2,7	3,8	mΩ
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 300 A, V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C <sub>chiplev.</sub>		1,45	1,9	V
		T <sub>j</sub> = 150°C <sub>chiplev.</sub>		1,7	2,1	V
C <sub>ies</sub>	V <sub>CE</sub> = 25, V <sub>GE</sub> = 0 V	f = 1 MHz		18,4		nF
C <sub>oes</sub>				1,14		nF
C <sub>res</sub>				0,54		nF
Q <sub>G</sub>	V <sub>GE</sub> = -15V...+15V			3900		nC
R <sub>Gint</sub>	T <sub>j</sub> = °C			1		Ω
t <sub>d(on)</sub>	R <sub>Gon</sub> = 2,2 Ω di/dt = 3400 A/μs	V <sub>CC</sub> = 300V I <sub>C</sub> = 300A		140		ns
t <sub>r</sub>				89		ns
E <sub>on</sub>	R <sub>Goff</sub> = 2,2 Ω di/dt = 3400 A/μs	T <sub>j</sub> = 125 °C V <sub>GE</sub> = --15V/+15V		3,5		mJ
t <sub>d(off)</sub>				433		ns
t <sub>f</sub>				116		ns
E <sub>off</sub>				10,1		mJ
R <sub>th(j-c)</sub>	per IGBT			0,15		K/W



SEMITRANS® 5

## Trench IGBT Modules

### SKM300MLI066TAT

#### Features

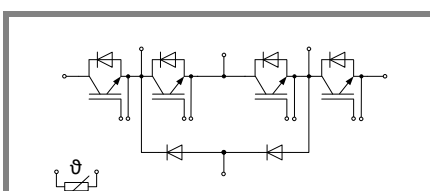
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$  with positive temperature coefficient
- Integrated NTC temperature sensor

#### Typical Applications\*

- UPS
- 3 Level Inverter

#### Remarks

- Case temperature limited to  $T_c = 125^\circ\text{C}$  max
- Recommended  $T_{op} = -40..+150^\circ\text{C}$  for IGBT;  
 $T_{op} = -40..+125^\circ\text{C}$  for diode
- $T_{vj}$  is intended as absolute maximum rating, limited by diode
- Fig.2 is referred to IGBT current capability



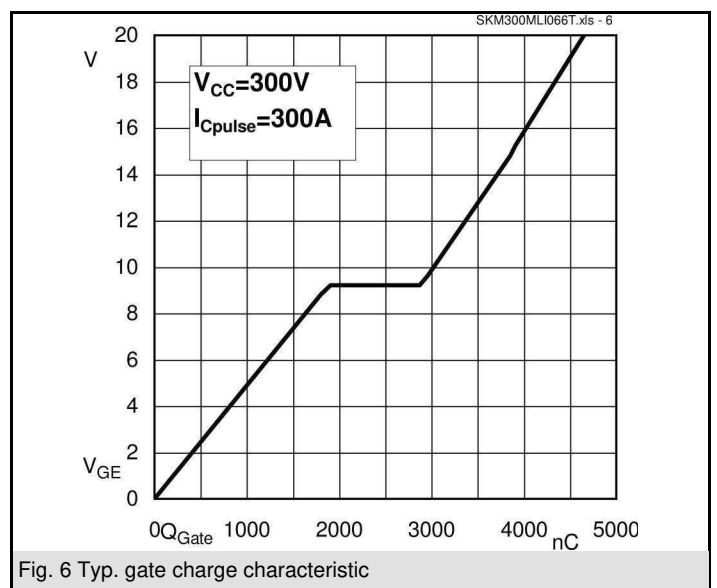
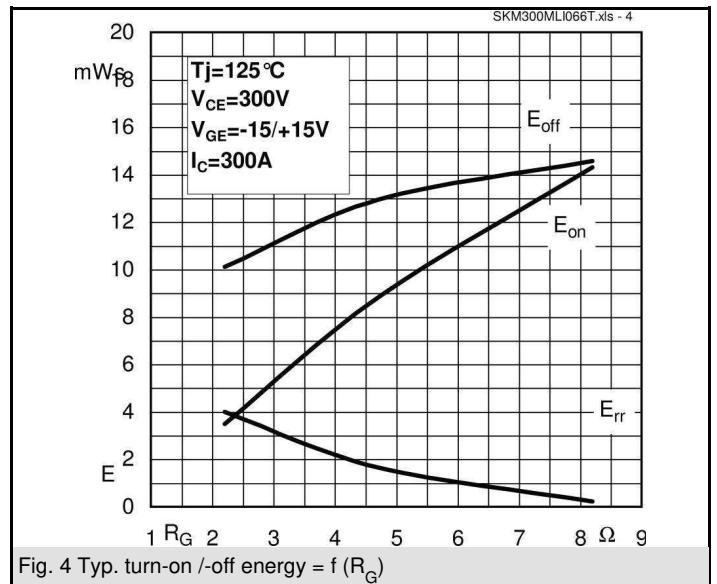
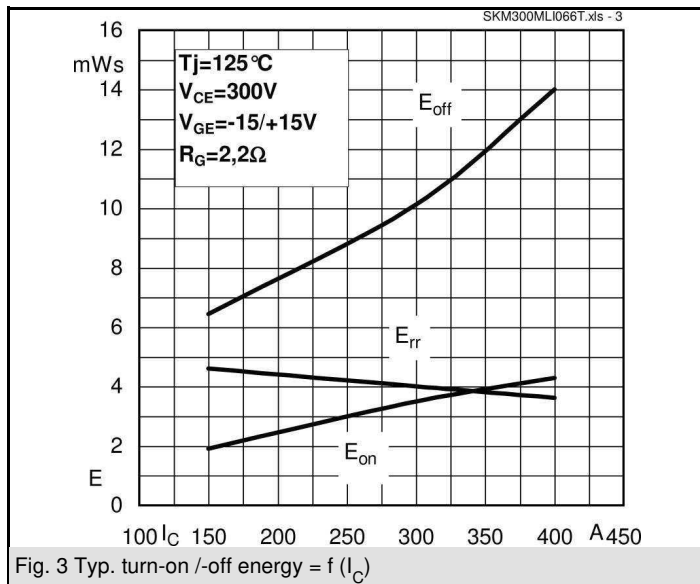
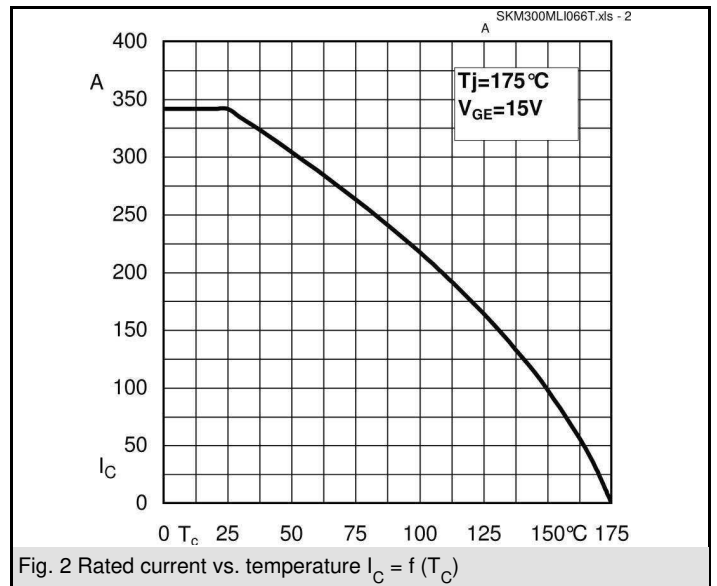
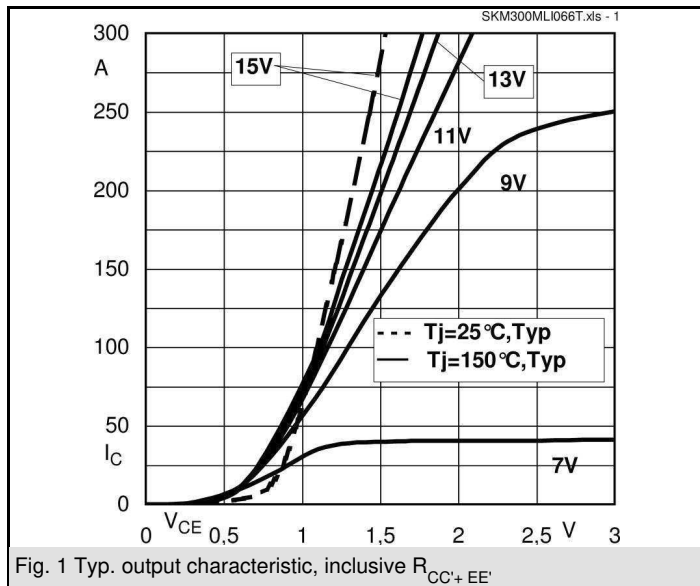
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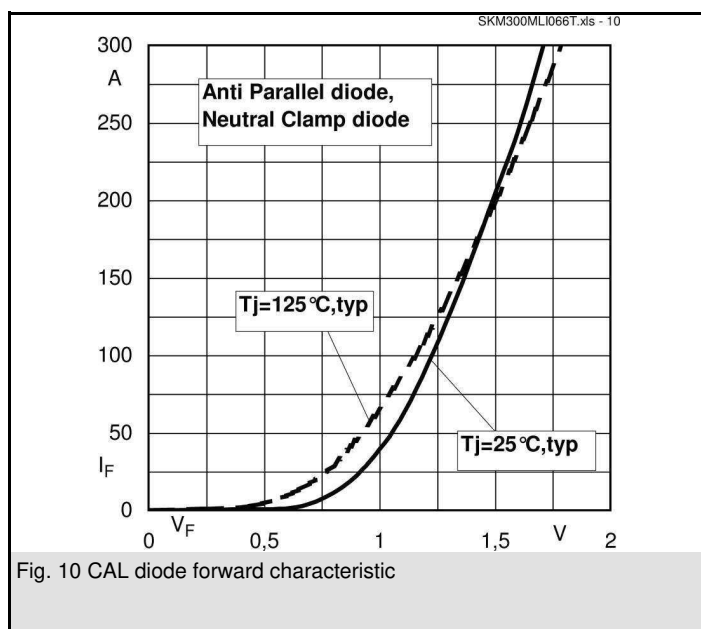
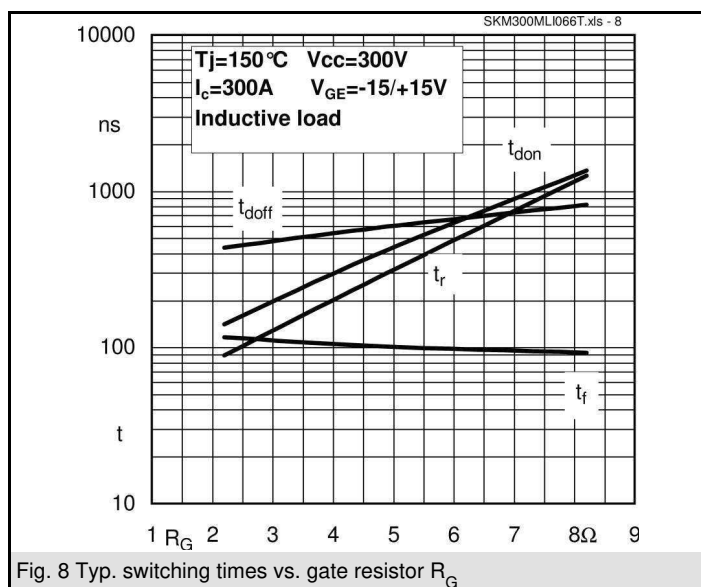
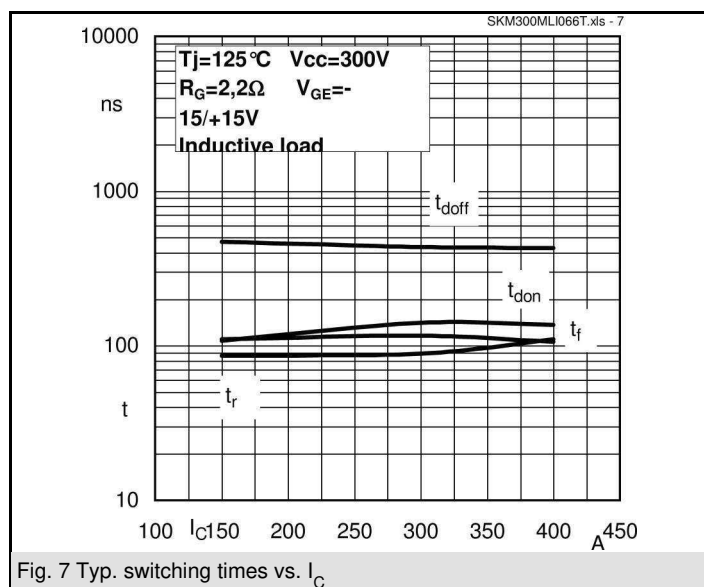
Characteristics						
Symbol	Conditions		min.	typ.	max.	Units
Inverse Diode						
V <sub>F</sub> = V <sub>EC</sub>	I <sub>Fnom</sub> = 245 A; V <sub>GE</sub> = 0 V	T <sub>j</sub> = 25 °C <sub>chiplev.</sub>		1,35	1,6	V
		T <sub>j</sub> = 125 °C <sub>chiplev.</sub>		1,35	1,6	V
V <sub>F0</sub>		T <sub>j</sub> = 25 °C		1	1,1	V
		T <sub>j</sub> = 125 °C		0,9	1	V
r <sub>F</sub>		T <sub>j</sub> = 25 °C		1,42	2	mΩ
		T <sub>j</sub> = 125 °C		1,8	2,4	mΩ
I <sub>RRM</sub>	I <sub>F</sub> = 245 A	T <sub>j</sub> = 125 °C				A
Q <sub>rr</sub>						μC
E <sub>rr</sub>	V <sub>GE</sub> = -8 V; V <sub>CC</sub> = 300 V					mJ
R <sub>th(j-c)D</sub>	per diode			0,28		K/W
Free-wheeling diode (Neutral Clamp Diode)						
V <sub>F</sub> = V <sub>EC</sub>	I <sub>Fnom</sub> = 245 A; V <sub>GE</sub> = 0 V	T <sub>j</sub> = 25 °C <sub>chiplev.</sub>		1,35	1,6	V
		T <sub>j</sub> = 125 °C <sub>chiplev.</sub>		1,35	1,6	V
V <sub>F0</sub>		T <sub>j</sub> = 25 °C		1	1,1	V
		T <sub>j</sub> = 125 °C		0,9	1	V
r <sub>F</sub>		T <sub>j</sub> = 25 °C		1,42	2	V
		T <sub>j</sub> = 125 °C		1,8	2,4	V
I <sub>RRM</sub>	I <sub>F</sub> = 300 A	T <sub>j</sub> = 125 °C		194		A
Q <sub>rr</sub>	di/dt = 3400 A/μs			13		μC
E <sub>rr</sub>	V <sub>GE</sub> = 0 V; V <sub>CC</sub> = 300 V			4		mJ
R <sub>th(j-c)FD</sub>	per diode			0,28		K/W
R <sub>th(c-s)</sub>	per module				0,038	K/W
M <sub>s</sub>	to heat sink M6		3		5	Nm
M <sub>t</sub>	to terminals M6		2,5		5	Nm
w					310	g
Temperature sensor						
R <sub>100</sub>	T <sub>s</sub> = 100 °C (R <sub>25</sub> = 5kΩ)			493 ± 5 %		Ω
						K

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

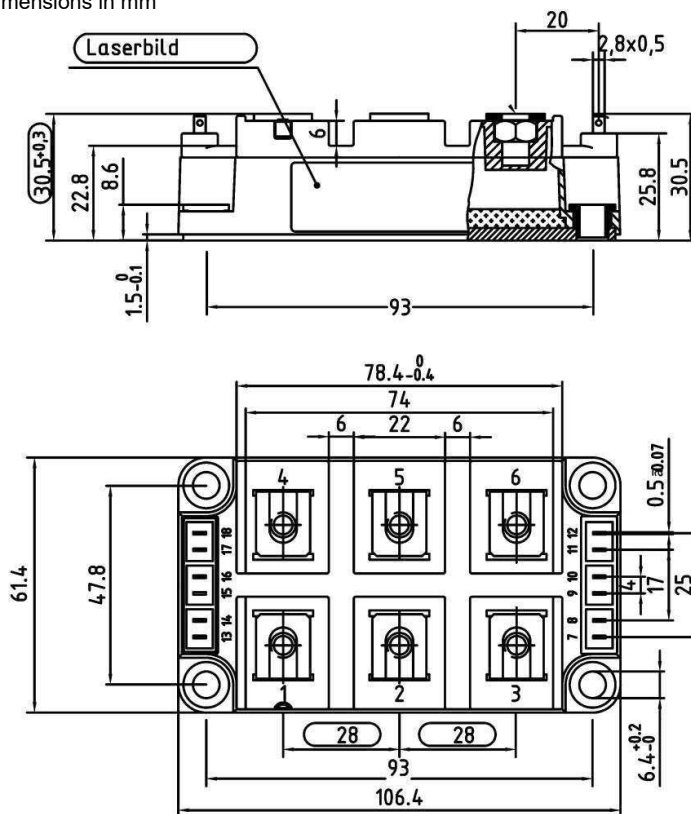
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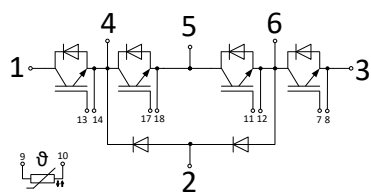




Dimensions in mm



Case D62



MLI-TAT

Case D62